

PHOTOSENSITIVE ADHESIVE COMPOSITION AND SEMICONDUCTOR DEVICE

ABSTRACT

5 A photosensitive adhesive composition of the present invention includes (A) an alkali-soluble resin, (B) a photo-acid-generating agent, (C) an epoxy compound, and (D) a phenolic compound having a melting point of 50°C to 150°C. When used as an adhesive layer that adheres semiconductor elements
10 together, a cured substance of the photosensitive adhesive composition of the present invention is capable of reducing the generation of air bubbles (voids) in the interfaces between the semiconductor element and the adhesive layer and, even when air bubbles are generated in the interfaces, is capable of removing
15 the generated air bubbles. As a result, it is possible to enhance the adhesiveness (adhesion properties) between semiconductor elements.

Fig. 1 accompanies the abstract.